

BRC50N06IP

Rev.A Jun.-2022



DATA SHEET

/ Revised record

A	2019.12.24				
A	2021-12-24	6-7	TO-252#		
A	2022-6-17		BRC50N06DP 251		

/ Descriptions

TO-251 N-CHANNEL MOSFET in a TO-251 Plastic Package.

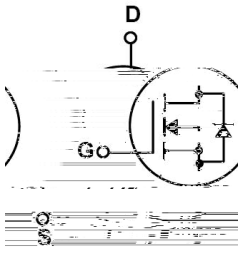
/ Features

Low $R_{DS(on)}$, low gate charge, low C_{rss} , fast switching, Trench Technologies, HF Product.

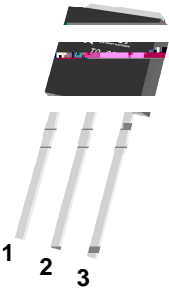
/ Applications

Suited for low voltage applications such as automotive, DC/DC Converters, and high efficiency switching for power management in portable and battery operated products.

/ Equivalent Circuit



/ Pinning



PIN 1 G PIN 2 D PIN 3 S

/ Marking

? @ A B C fi See Marking Instructions.

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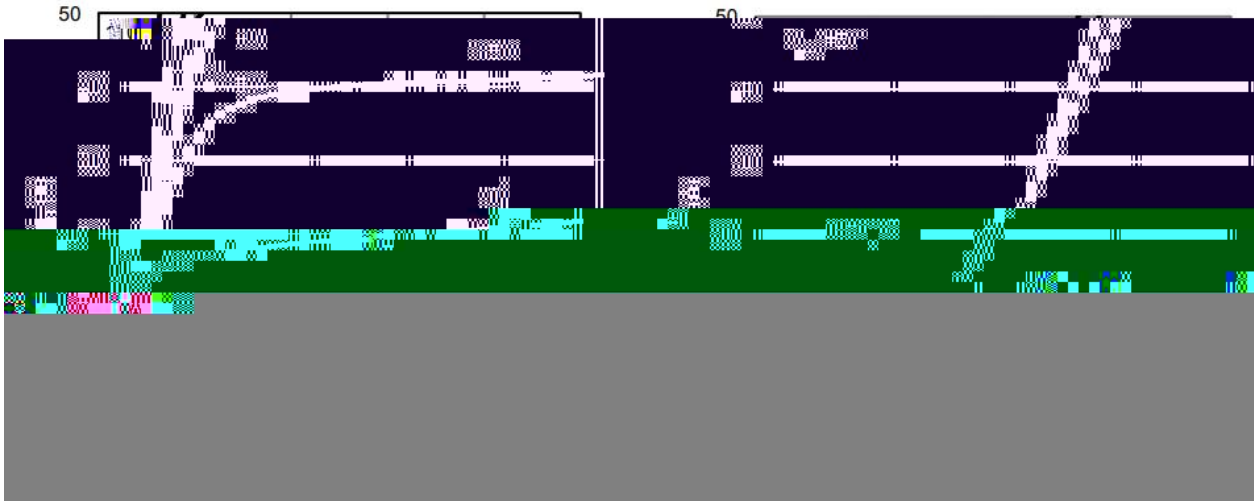


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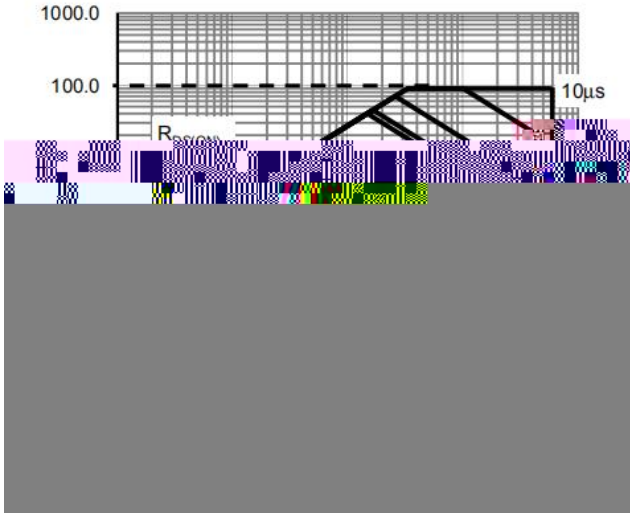
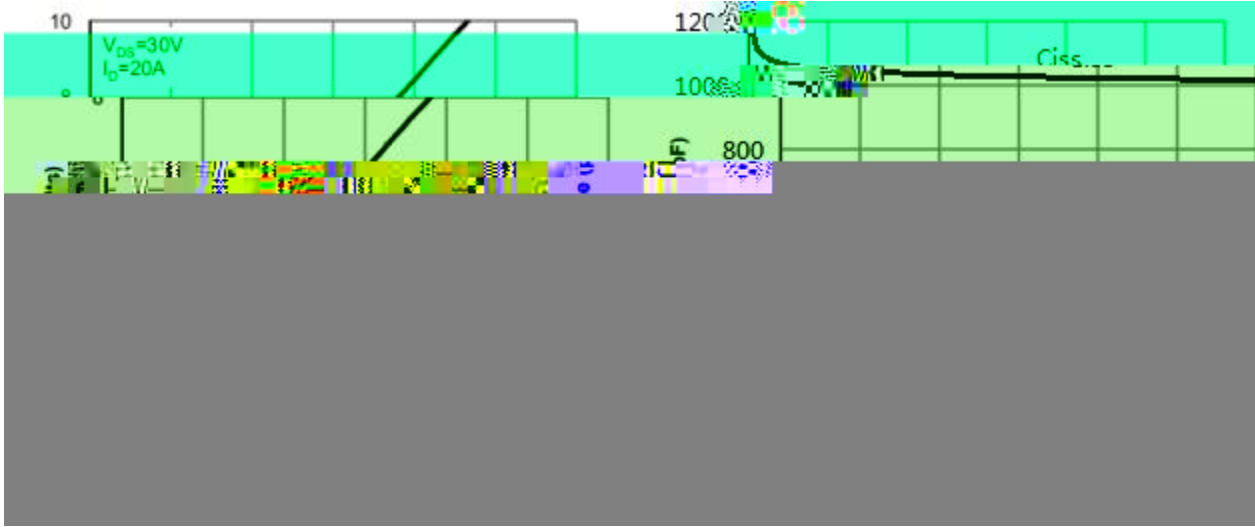
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	U_{DSS}	60	V

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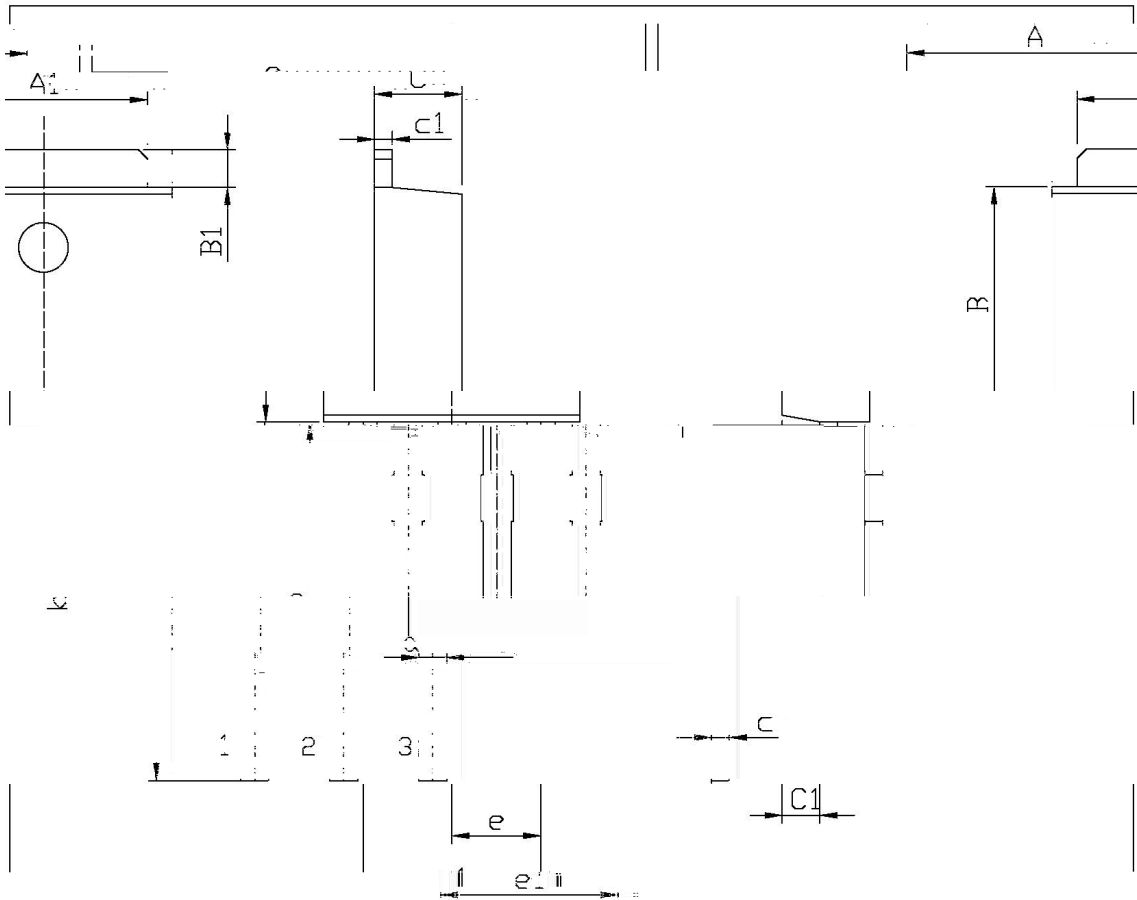
/ Electrical Characteristic Curve



/ Electrical Characteristic Curve

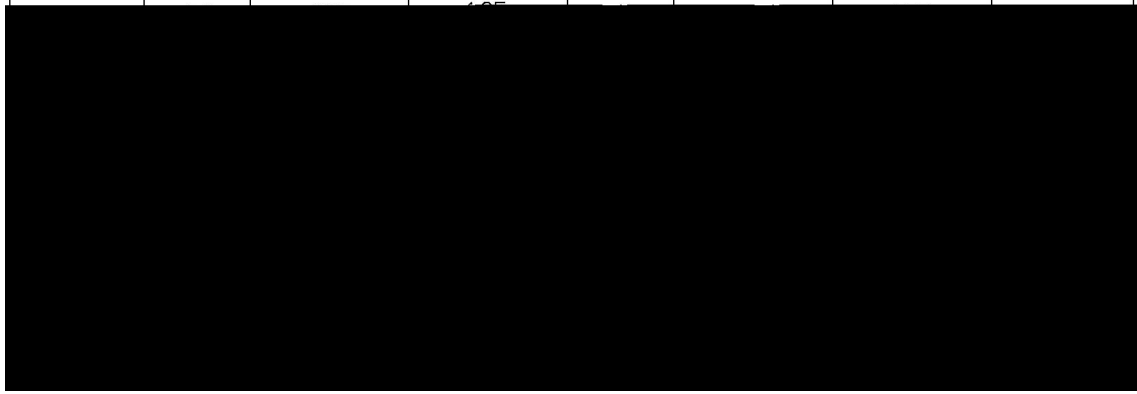


/ Package Dimensions

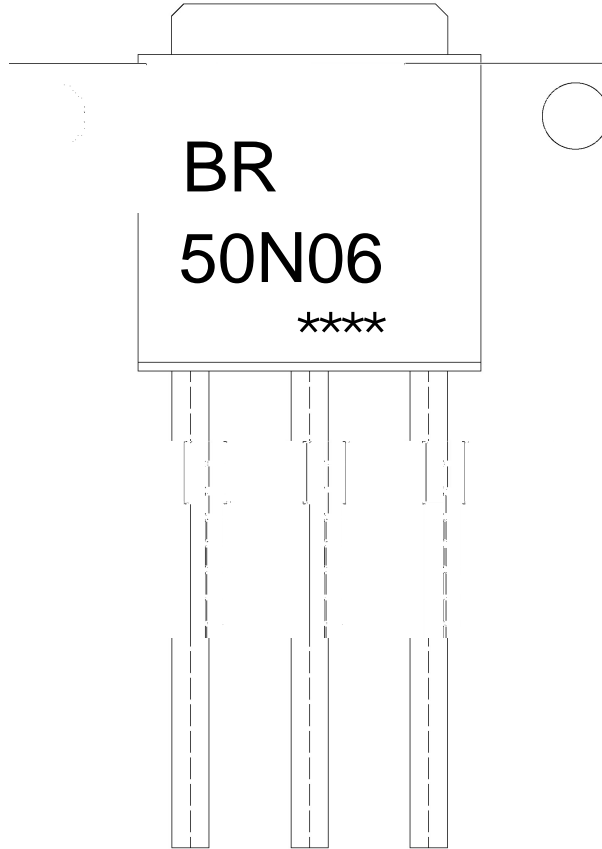


单位: mm

Dimensions in Millimeters		Dimensions in Millimeters		Unit
6.25	0.45	0.55	0.55	mm



/ Marking Instructions



说明：

BR： 为公司代码

50N06： 为型号代码

****： 为生产批号代码，随生产批号变化

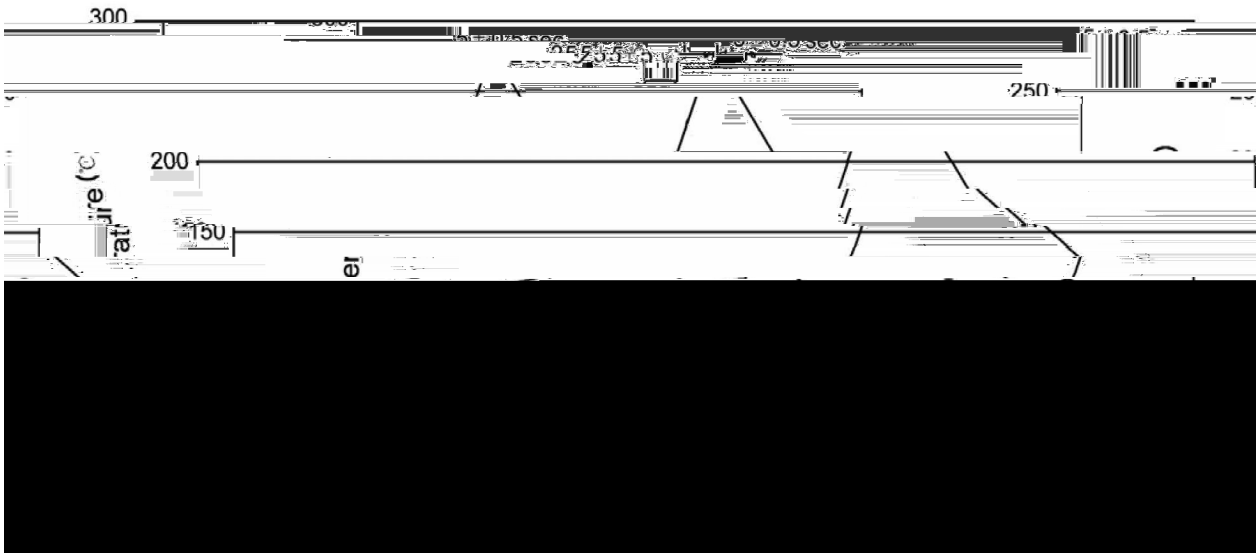
Note:

BR: Company Code

50N06: Product Type Code

****: Not No. Code, code change with Not No

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-------|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5 | sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BÜNK

Package Type 封装形式	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units 包装数量	Dimension 包装尺寸	Unit: mm ³
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